

Accepted Manuscript

Simulation of the thermal shock behavior of ultra-high temperature ceramics with the consideration of temperature-dependent crack propagation criterion and interaction between thermal shock cracks evolution and thermal conduction

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PII: S0997-7538(18)30096-2

DOI: [10.1016/j.euromechsol.2018.05.016](https://doi.org/10.1016/j.euromechsol.2018.05.016)

Reference: EJMSOL 3616

To appear in: *European Journal of Mechanics / A Solids*

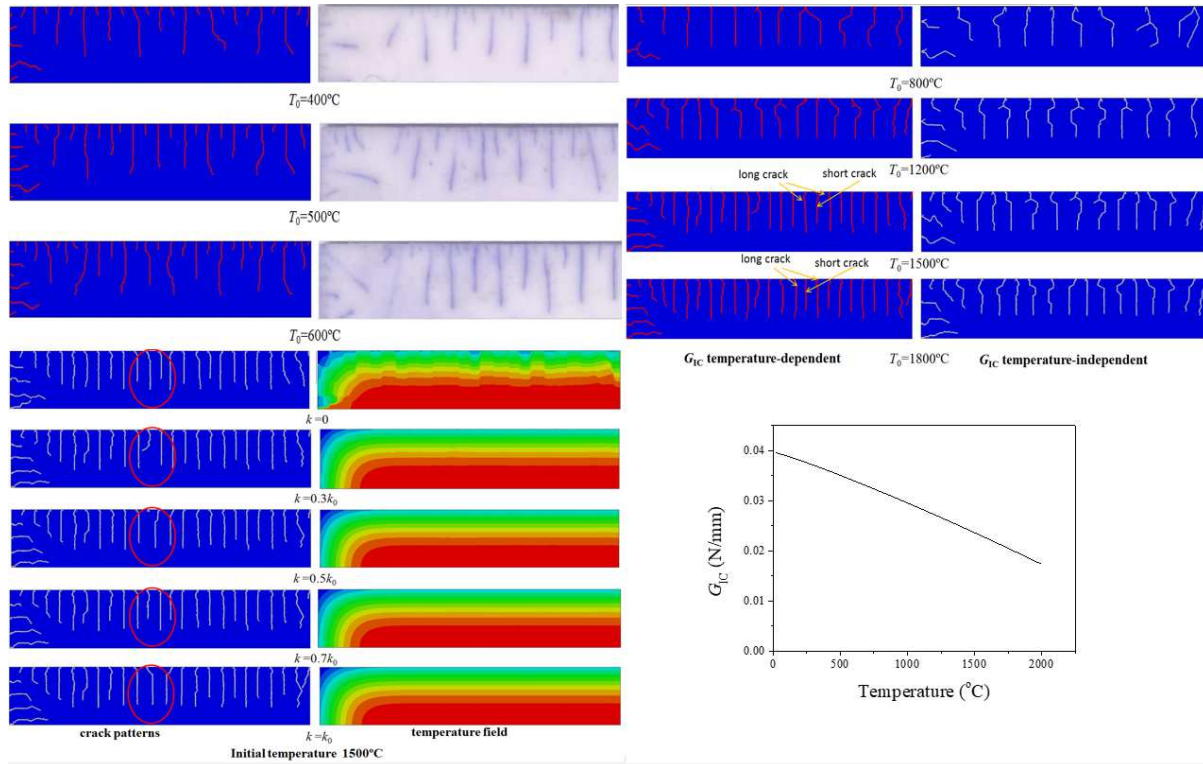
Received Date: 4 February 2018

Revised Date: 26 April 2018

Accepted Date: 24 May 2018

Please cite this article as: Li, D., Li, W., Wang, R., Kou, H., Simulation of the thermal shock behavior of ultra-high temperature ceramics with the consideration of temperature-dependent crack propagation criterion and interaction between thermal shock cracks evolution and thermal conduction, *European Journal of Mechanics / A Solids* (2018), doi: 10.1016/j.euromechsol.2018.05.016.

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